TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

2SK3466

Chopper Regulator Applications

Unit: mm

• Low drain-source ON resistance: RDS (ON) = 1.35Ω (typ.)

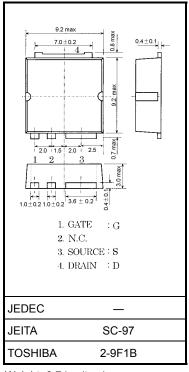
• High forward transfer admittance: $|Y_{fs}| = 4.0 \text{ S (typ.)}$

• Low leakage current: $IDSS = 100 \mu A (max) (VDS = 500 V)$

• Enhancement model: $V_{th} = 2.0 \text{ to } 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$

Absolute Maximum Ratings (Ta = 25°C)

Characteristics			Symbol	Rating	Unit	
Drain-source voltage			V_{DSS}	500	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)			V_{DGR}	500	V	
Gate-source voltage			V _{GSS}	±30	V	
Drain current	DC	(Note 1)	ΙD	5	Α	
	Pulse	(Note 1)	I _{DP}	20	A	
Drain power dissipation (Tc = 25°C)			P_{D}	50	W	
Single pulse avalanche energy (Note 2)			EAS	180	mJ	
Avalanche current			I _{AR}	5	Α	
Repetitive avalanche energy (Note 3)			E _{AR}	5	mJ	
Channel temperature			T _{ch}	150	°C	
Storage temperature range			T _{stg}	-55 to 150	°C	



Weight: 0.74 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.5	°C/W

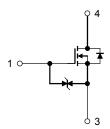
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: $V_{DD}=90~V,~T_{ch}=25^{\circ}C$ (initial), $L=12.2~mH,~R_{G}=25~\Omega,~I_{AR}=5~A$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Please handle with caution.

Circuit Configuration



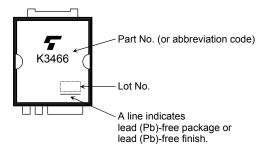
Electrical Characteristics (Ta = 25°C)

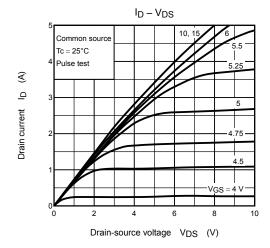
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Drain cut-OFF cu	rain cut-OFF current		V _{DS} = 500 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source brea	akdown voltage	V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	500 — -		_	V
Gate threshold vo	ate threshold voltage		V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source ON	Drain-source ON resistance		V _{GS} = 10 V, I _D = 5 A		1.35	1.50	Ω
Forward transfer	admittance	Y _{fs}	V _{DS} = 10 V, I _D = 5 A	2.5	4.0	_	S
Input capacitance		C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	780	_	pF
Reverse transfer capacitance		C _{rss}		_	60	_	
Output capacitance		C _{oss}]	_	200	_	
Switching time	Rise time	t _r	$\begin{array}{c c} 10 \text{ V} & \text{I}_D = 2.5 \text{ A} & \text{Output} \\ \hline 0 \text{ V} & \text{S} & \text{S} \\ 15 \Omega & \text{S} & \text{RL} = 90 \Omega \\ \hline \end{array}$	_	12	_	- ns
	Turn-ON time	t _{on}		_	25		
	Fall time	t _f		_	15	_	
	Turn-OFF time	t _{off}	Duty ≤ 1%, t _w = 10 μs	_	60		
Total gate charge (gate-source plus gate-drain)		Qg			17		
Gate-source charge		Q _{gs}	$V_{DD} \simeq 400 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$	_	11	_	nC
Gate-drain ("miller") charge		Q _{gd}			6		

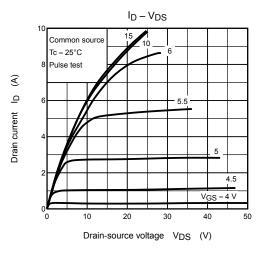
Source-Drain Ratings and Characteristics (Ta = 25°C)

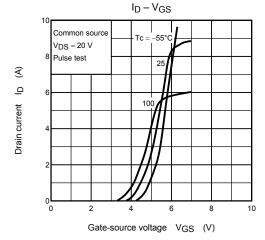
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DSF}	_	_	_	5	Α
Pulse drain reverse current (Note 1)	I _{DRP}	_	_	_	20	Α
Forward voltage (diode)	V _{DSF}	I _{DR} = 5 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	$I_{DR} = 5 \text{ A}, V_{GS} = 0 \text{ V},$	_	1400	_	ns
Reverse recovery charge	Q _{rr}	dI _{DR} /dt = 100 A/μs	_	9	_	μС

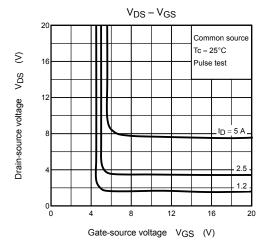
Marking

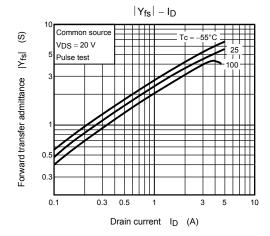


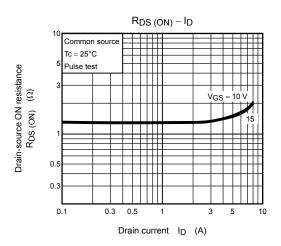


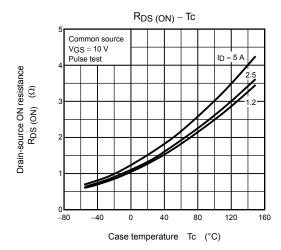


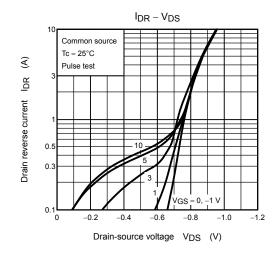


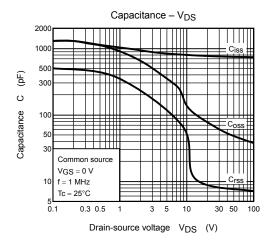


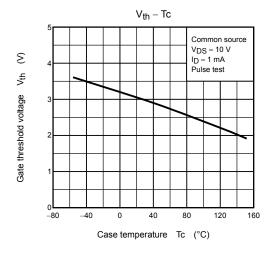


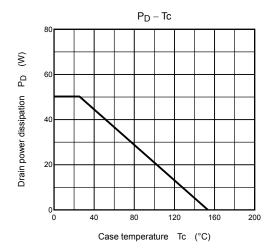


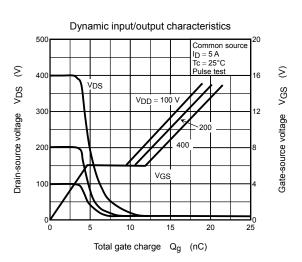


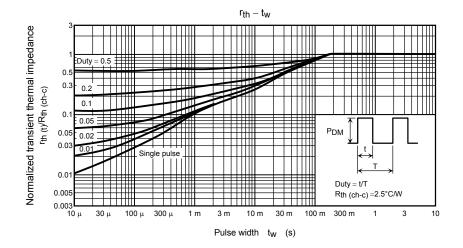




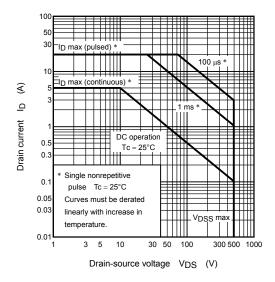


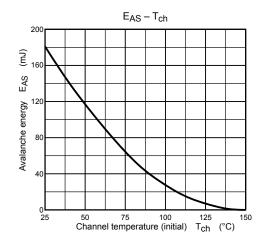


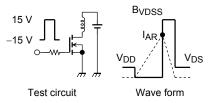




Safe operating area







$$\begin{aligned} R_G &= 25~\Omega \\ V_{DD} &= 90~V,~L = 12.2~mH \end{aligned} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left(\frac{BVDSS}{BVDSS} - VDD \right)$$

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